

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Kenji ITOH et al.

Serial No.: 09/412,510

Filed: October 5, 1999

For: PROCESS FOR TREATING A  
SUBSTRATE WITH A PLASMA  
(As Amended)



Art Unit: 1762

Examiner: M. Padgett

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on 2-1-01

*Linda M. Luman*

02/09/2001 TGEDAMU1 00000016 09412510

01 FC:102

80.00 OP

**AMENDMENT**

Honorable Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action dated September 1, 2000, please amend the above-identified application as follows:

**IN THE TITLE:**

Please replace the title of the present invention with the following:

-- PROCESS FOR TREATING A SUBSTRATE WITH A PLASMA--.

**IN THE SPECIFICATION:**

Please delete the first sentence of the specification and insert in its place

This application is a Divisional of U.S. Patent 6,001,431, filed February 21, 1996, which itself is a Continuation of Application Serial No. 08/173,961, filed December 28, 1993, now abandoned.--

Please amend the specification as follows:

Page 2, line 11, change "field" to --fields--;

line 23, before "advantage" insert --cost--;

line 24, delete "in cost".

Page 4, line 27, before "plane" insert --a--.

RECEIVED  
FEB 12 2001  
TOLSON MAIL ROOM